IEEE 802.3 Ethernet Working Group
DRAFT Liaison Communication

Source:	IEEE 802.3 Working Group[1]	
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From:	David Law	Chair, IEEE 802.3 Ethernet Working Group [redacted]
Subject:	Request for Information related to 400 Gb/s/lane Electrical Connectors	
Approval	Agreed at IEEE 802.3 Plenary meeting, Bangkok, Thailand, 12 Nov 2026	

Dear Colleagues,

In October 2026, the IEEE P802.3dv Task Force was approved. This project will specify changes to IEEE Std 802.3 that will define specifications for 400 Gb/s/lane signaling for electrical interconnects and single-mode fiber optical interconnects with reaches up to 500 meters for 400 GbE, 800 GbE, and 1.6 TbE.

Based on presentations at the recent European Conference on Optical Communications and Ethernet Alliance Technology Exploration Forum (TEF) events, it has come to the attention of the Task Force that 400 Gb/s/lane signaling over different connector solutions for OSFP and XPO are emerging.

The IEEE 802.3 Ethernet community is moving quickly to address the AI market need. In that interest, it would request that your respective organizations consider providing any relevant information it has related to your connectors that would assist the IEEE P802.3dv Task Force participants in developing its 400 Gb/s/lane electrical signaling specifications.

[1] This document solely represents the views of the IEEE 802.3 Working Group, and does not necessarily represent a position of the IEEE, the IEEE Standards Association, or IEEE 802.

Please note that the Task Force has not yet made any decisions in relation to PAM4 or PAM6 modulation for electrical interconnects.

Please note that any information related to the overview of the module, the respective electrical connector, its pinout, its performance, or any relevant channel data, including assumptions related to the host and module ILdd, would be useful to the Task Force.

For further information on task force activities, please see https://www.ieee802.org/3/dv/index.html.

We look forward to your response.

Sincerely,

David Law

Chair, IEEE 802.3 Ethernet Working Group

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